Annex III

<u>List of activities for which accreditation has been terminated</u> (Notification letter no. 231-3; Effective date of termination: 30 September 2014)

.TEST .CATEGORY	ITEM, MATERIAL OR PRODUCT TESTED	SPECIFIC TEST OR PROPERTY MEASURED	SPECIFICATION, STANDARD METHOD OR TECHNIQUE USED
測試類別	.測試項目、材料或產品	.特定測試或量度的特性	規範、標準方法或應用技術
PHYSICAL and MECHANICAL TESTING 物理及機械測試	Integrated Circuit Components:-		
TESTING 物理及機械測試	Components: Nonhermetic solid state surface mount devices	Examination of internal construction of solid state surface mount devices using microscope after decapsulation for the following items: - Part number - Markings - Manufacturer - Copyright date - Wafer art - No die or blank die - Damaged wafers - OCM rejection dots	MIL-STD-883H Method 2014: 1974